

# APPROVAL SHEET

**MR12, MR08, MR06, MR04**

**±1%, ±5%**

Thick film General Purpose Chip Resistors

Size 1206, 0805, 0603, 0402

Automotive & Military Compliant

RoHS Exemption Free Lead<100ppm

\*Contents in this sheet are subject to change without prior notice.

## FEATURE

1. High reliability and stability  $\pm 1\%$
2. Automotive AEC Q-200 & Military MIL-STD Compliant
3. 100% CCD inspection
4. RoHS Exemption free and Halogen free products

## APPLICATION

- Automotive application
- Consumer electrical equipment
- EDP, Computer application
- Telecom application

## DESCRIPTION

The LEAD FREE resistors are constructed in a high grade ceramic body (aluminum oxide). Internal metal electrodes are added at each end and connected by a LEAD FREE resistive paste that is applied to the top surface of the substrate. The composition of the paste is adjusted to give the approximate resistance required and the value is trimmed to within tolerance by laser cutting of this resistive layer.

The resistive layer is covered with a protective coat. For all series, overcoat is WATER BLUE color. Finally, the two external end terminations are added. For ease of soldering the outer layer of these end terminations is a Tin (lead free) alloy.

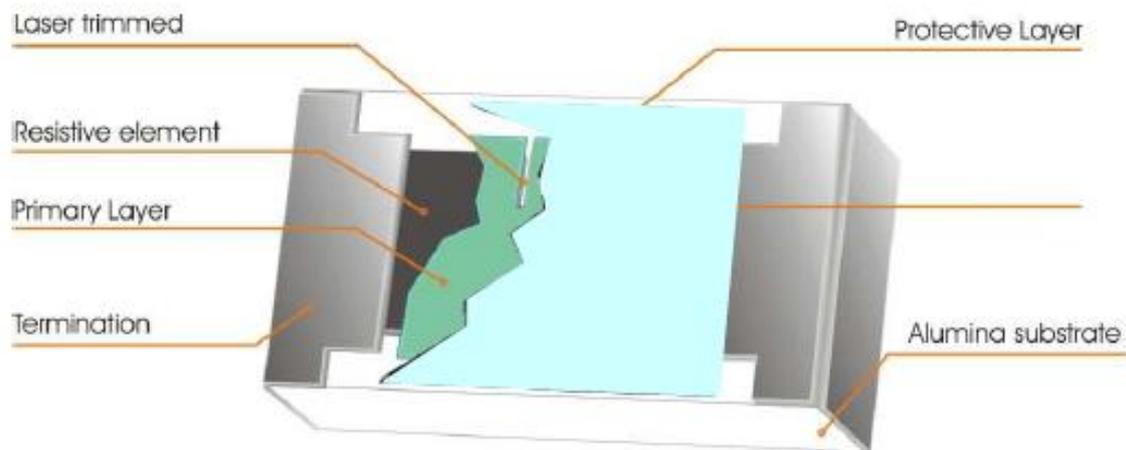


Fig 1. Construction of a Chip-R

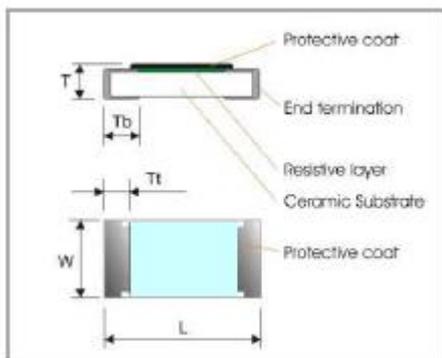
**QUICK REFERENCE DATA**

Item	General Specification							
	MR12		MR08		MR06		MR04	
Series No.	MR12		MR08		MR06		MR04	
Size code	1206(3216)		0805(2012)		0603(1608)		0402(1005)	
Resistance Range	1Ω~10MΩ (±5% tolerance), Jumper 1Ω~10MΩ (±1% tolerance)							
Resistance Tolerance	±1% E96/E24	±5% E24	±1% E96/E24	±5% E24	±1% E96/E24	±5% E24	±1% E96/E24	±5% E24
TCR (ppm/°C)								
R > 1MΩ	≤ ± 200		≤ ± 200		≤ ± 200		≤ ± 200	
10Ω < R ≤ 1MΩ	≤ ± 100		≤ ± 100		≤ ± 100		≤ ± 100	
R ≤ 10Ω	-200~+400		-200~+400		-200~+400		-200~+400	
Max. dissipation @ T <sub>amb</sub> =70°C	1/4 W		1/8 W		1/10 W		1/16 W	
Max. Operation Voltage	200V		150V		75V		50V	
Max. Overload Voltage	400V		300V		150V		100V	
Operation temperature	-55/+155C							

Note :

- Max. Operation Voltage : So called RCWV (Rated Continuous Working Voltage) is determined by  

$$RCWV = \sqrt{\text{Rated Power} \times \text{Resistance Value}} \text{ or Max. RCWV listed above, whichever is lower.}$$
- The resistance of Jumper is defined <0.05Ω.

**DIMENSIONS (unit : mm)**

	MR12	MR08	MR06	MR04
<b>L</b>	3.10 ± 0.10	2.00 ± 0.10	1.60 ± 0.10	1.00 ± 0.05
<b>W</b>	1.60 ± 0.10	1.25 ± 0.10	0.80 ± 0.10	0.50 ± 0.05
<b>T</b>	0.60 ± 0.15	0.50 ± 0.15	0.45 ± 0.15	0.35 ± 0.05
<b>Tb</b>	0.45 ± 0.20	0.40 ± 0.20	0.30 ± 0.15	0.25 ± 0.10
<b>Tt</b>	0.50 ± 0.20	0.40 ± 0.20	0.30 ± 0.10	0.20 ± 0.10

No MARKING for all series.

## FUNCTIONAL DESCRIPTION

### Product characterization

Standard values of nominal resistance are taken from the E24 series for resistors with a tolerance of  $\pm 5\%$ , and E24+E96 series for resistors with a tolerance of  $\pm 1\%$ . The values of the E24/E96 series are in accordance with "IEC publication 60063".

### Derating

The power that the resistor can dissipate depends on the operating temperature; see Fig.2.1

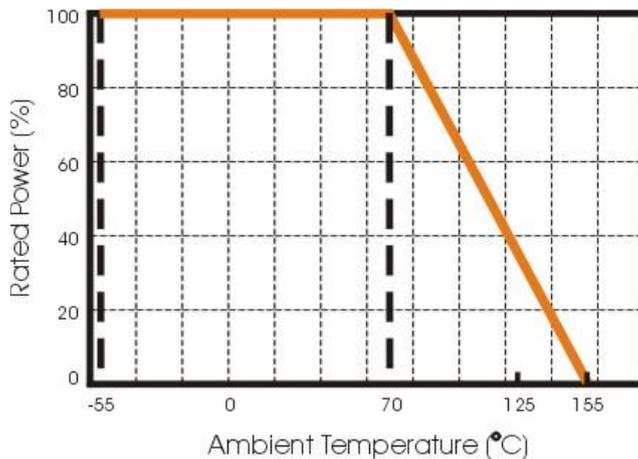


Figure 2.1 Maximum dissipation in percentage of rated power as a function of the ambient temperature

## MOUNTING

Due to their rectangular shapes and small tolerances, Surface Mountable Resistors are suitable for handling by automatic placement systems.

Chip placement can be on ceramic substrates and printed-circuit boards (PCBs).

Electrical connection to the circuit is by individual soldering condition.

The end terminations guarantee a reliable contact.

### SOLDERING CONDITION

The robust construction of chip resistors allows them to be completely immersed in a solder bath 260°C for 10 seconds. Therefore, it is possible to mount Surface Mount Resistors on one side of a PCB and other discrete components on the reverse (mixed PCBs).

Surface Mount Resistors are tested for solderability at 235°C during 2 seconds. The test condition for no leaching is 260°C for 30 seconds. Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 3.

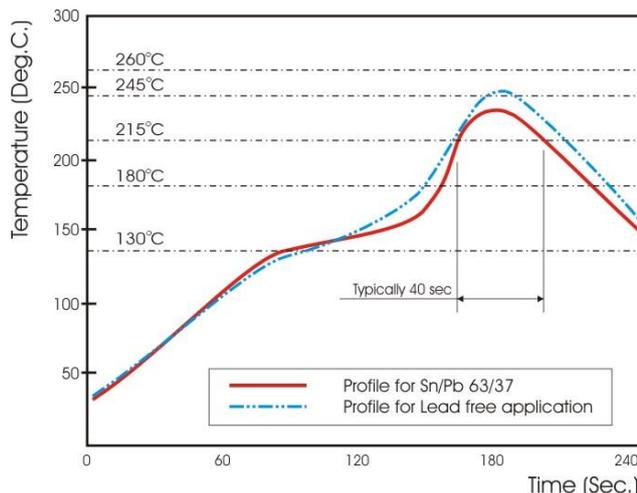


Fig 3. Infrared soldering profile for Chip Resistors

### CATALOGUE NUMBERS

The resistors have a catalogue number starting with .

MR12	X	472_	J	T	R
<b>Automotive code</b>	<b>Type code</b>	<b>Resistance code</b>	<b>Tolerance</b>	<b>Packaging code</b>	<b>Termination code</b>
MR12 : 1206	X :	±5%, E24: 2 significant digits followed by no. of zeros and a blank	F : ±1%	T : 7" Reeled taping	R = Lead free LEAD<100ppm
MR08 : 0805	±5%, 1Ω ~ 10MΩ	220Ω = 221_	J : ±5%	D : 7" Reel 20K/RL 0402 size	
MR06 : 0603	±1%, 10Ω ~ 1MΩ	4K7 = 472_	P : Jumper	Q : 10" Reeled taping	
MR04: 0402	W :	10Ω = 100_		G : 13" Reeled taping	
	±1%, < 10Ω; >1MΩ	1Ω =1R0_		B : Bulk	
		("_" means a blank )			
		<b>Resistance code</b>			
		±1%, E24+E96: 3 significant digits followed by no. of zeros			
		E96: 37.4KΩ = 3742			
		E24: 220Ω = 2200			
		4K7 = 4701			
		10Ω = 10R0			
		1Ω =1R00			

MR12,MR08,MR06:

1. Reeled tape packaging : 8mm width paper taping 5000pcs per 7" reel, 10kpcs per 10" reel, 20kpcs per 13" reel.
2. Bulk packaging : 5000pcs per poly-bag

MR04:

1. Reeled tape packaging : 8mm width paper taping 10,000pcs per reel,
2. Bulk packaging : 10,000pcs per poly-bag

## TEST AND REQUIREMENTS

Essentially all tests are carried out according to the schedule of IEC publication 115-8, category **LCT/UCT/56**(rated temperature range : **Lower Category Temperature, Upper Category Temperature**; damp heat, long term, 56 days). The testing also meets the requirements specified by EIA, EIAJ and JIS.

The tests are carried out in accordance with IEC publication 68, "Recommended basic climatic and mechanical robustness testing procedure for electronic components" and under standard atmospheric conditions according to IEC 60068-1, sub-clause 5.3. Unless otherwise specified, the following value supplied :

Temperature: 15 °C to 35 °C.

Relative humidity: 45% to 75%.

Air pressure: 86kPa to 106 kPa (860 mbar to 1060 mbar).

All soldering tests are performed with mildly activated flux.

TEST	PROCEDURE / TEST METHOD	REQUIREMENTS	
		Resistance	0Ω
Electrical Characteristics <b>JISC5201-1: 1998</b> Clause 4.8	- DC resistance values measurement - Temperature Coefficient of Resistance (T.C.R) Natural resistance change per change in degree centigrade. $\frac{R_2 - R_1}{R_1(t_2 - t_1)} \times 10^6 \text{ (ppm/}^\circ\text{C)} \quad t_1 : 20^\circ\text{C}+5^\circ\text{C}-1^\circ\text{C}$ R <sub>1</sub> : Resistance at reference temperature R <sub>2</sub> : Resistance at test temperature	Within the specified tolerance Refer to "QUICK REFERENCE DATA"	
Resistance to soldering heat (R.S.H) <b>MIL-STD-202 method 210</b>	Un-mounted chips completely immersed for 10±1second in a SAC solder bath at 270°C±5°C	ΔR/R max. ±(0.5%+0.05Ω) No visible damage	<50mΩ
Solderability <b>J-STD-002</b>	a) Bake the sample for 155°C dwell time 4hrs/ solder dipping 235°C/ 5sec. b) Steam the sample dwell time 8 hrs/ solder dipping 215°C/ 5sec. c) Steam the sample dwell time 8 hrs/ solder dipping 260°C/ 7sec.	95% coverage min., good tinning and no visible damage	
Temperature cycling <b>JESD22 method JA-104</b>	1000 cycles, -55°C ~ +155°C, dwell time 30min	ΔR/R max. ±(0.5%+0.05Ω) No visible damage	<50mΩ
Moisture Resistance <b>MIL-STD-202 method 106</b>	65±2°C, 80~100% RH, 10 cycles, 24 hours/ cycle	ΔR/R max. ±(0.5%+0.05Ω) No visible damage	<50mΩ
Bias Humidity <b>MIL-STD-202 method 103</b>	1000+48/-0 hours; 85°C, 85% RH, 10% of operation power	ΔR/R max. ±(1%+0.05Ω) No visible damage	<50mΩ
Operational Life <b>MIL-STD-202 method 108</b>	1000+48/-0 hours; 35% of operation power, 125±2°C	ΔR/R max. ±(1%+0.05Ω) No visible damage	<50mΩ
Short Time Overload <b>JIS C 5201-1 Clause 4.13</b>	Permanent resistance change after a 5 second application of a voltage 2.5 times rated voltage or max. overload voltage, whichever is less.	ΔR/R max. ±(2%+0.1Ω) No visible damage	<50mΩ

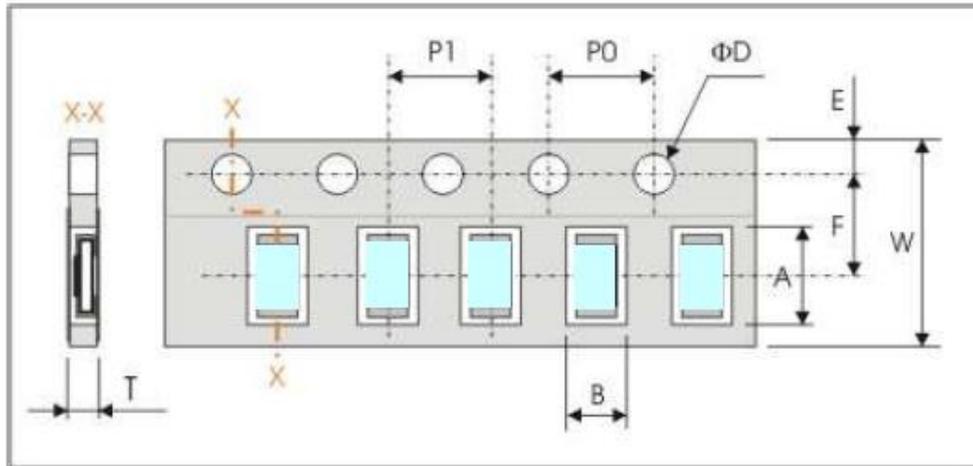
TEST	PROCEDURE / TEST METHOD	REQUIREMENTS	
		Resistance $\pm 5\%$ , $\pm 1\%$	0 $\Omega$
High Temperature Exposure <b>MIL-STD-202 method 108</b>	1000+48/-0 hours; without load in a temperature chamber controlled 155 $\pm$ 3 $^{\circ}$ C	$\Delta R/R$ max. $\pm(1\%+0.05\Omega)$ No visible damage	<50m $\Omega$
Mechanical Shock <b>MIL-STD-202 method 213</b>	Test 1/2 Sine Pulse/ 1500g peak/ normal duration: 6ms/ Velocity: 15.4ft/sec. Three shocks in each direction, total 18 shocks.	Within the specified tolerance. No visible damage	<50m $\Omega$
Board Flex <b>AEC-Q200-005</b>	Resistors mounted on a 90mm glass epoxy resin PCB(FR4), bending once 2mm for 10sec	$\Delta R/R$ max. $\pm(1.0\%+0.05\Omega)$ . No visible damage	<50m $\Omega$
Terminal strength <b>AEC-Q200-006</b>	Pressurizing force: 1.8Kg ( 1Kg for 0402 ), Test time: 60 $\pm$ 1sec.	No remarkable damage or removal of the terminations	
Resistance to Solvents <b>MIL-STD-202 Method 215</b>	Solvent is Isopropyl alcohol, immersion 3mins at 25 $^{\circ}$ C and brush 10 strokes with a toothbrush with a handle made of a non-reactive material (wet bristle), immersion and brush 3 times and then air blow dry	No superficial defect on marking, encapsulation, coating, appearance. Electrical characteristics within products specification and tolerance. Inspect at 3X max. for marking, inspect at 10X for part damage.	
Vibration <b>MIL-STD-202 method 204</b>	Test 5g's for 20min., 12 cycles each of 3 orientations	$\Delta R/R$ max. $\pm(1.0\%+0.05\Omega)$ No visible damage	<50m $\Omega$
Thermal shock <b>MIL-STD-202 method 107</b>	Test -55 to 155 $^{\circ}$ C / dwell time 15min/ Max transfer time 20sec 300cycles	$\Delta R/R$ max. $\pm(0.5\%+0.05\Omega)$ No visible damage	<50m $\Omega$
ESD <b>AEC-Q200-002</b>	Test contact 1.0KV ( 0.5KV for 0402 only)	$\Delta R/R$ max. $\pm(1\%+0.05\Omega)$ No visible damage	<50m $\Omega$

**TEST CONDITION FOR JUMPER (0  $\Omega$ )**

Item	MR12	MR08	MR06	MR04
Power Rating At 70 $^{\circ}$ C	1/4W	1/8W	1/10W	1/16W
Resistance	MAX.50m $\Omega$			
Rated Current	2.2A	1.6A	1.4A	1.1A
Peak Current	4.4A	3.2A	2.8A	2.2A
Operating Temperature	-55 ~ +155 $^{\circ}$ C			

**PACKAGING**

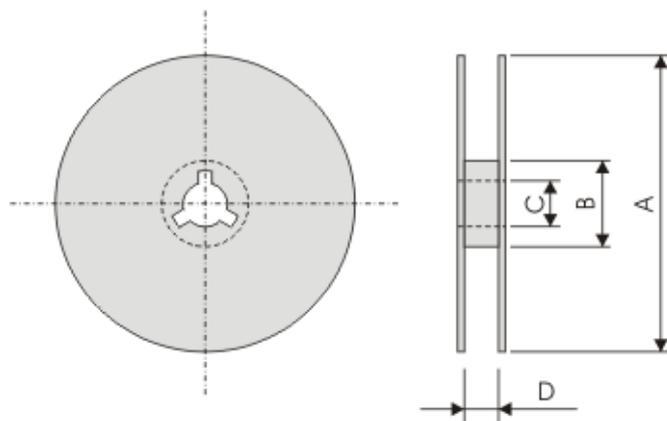
Paper Tape specifications (unit :mm)



Series No.	A	B	W	F	E
MR12	3.60±0.20	2.00±0.20	8.00±0.30	3.50±0.20	1.75±0.10
MR08	2.40±0.20	1.65±0.20			
MR06	1.90±0.20	1.10±0.20			
MR04	1.20±0.10	0.70±0.10			

Series No.	P1	P0	ΦD	T
MR12/08	4.00±0.10	4.00±0.10	Φ1.50 <sup>+0.1</sup> <sub>-0.0</sub>	Max. 1.0
MR06				0.65±0.05
MR04				0.40±0.05

**7" Reel dimensions**



Symbol	A	B	C	D
(unit : mm)	Φ178.0±2.0	Φ60.0±1.0	13.0±0.2	9.0±0.5